

SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL31B475KPHNNNF**
- Description : **CAP, 4.7 μ F, 10V, \pm 10%, X7R, 1206**

A. Samsung Part Number

CL **31** **B** **475** **K** **P** **H** **N** **N** **N** **F**
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor						
② Size	1206 (inch code)	L: 3.2 ± 0.2	mm	W: 1.6 ± 0.2	mm		
③ Dielectric	X7R	⑧ Inner electrode	Ni				
④ Capacitance	4.7 μF	Termination	Cu				
⑤ Capacitance tolerance	±10 %	Plating	Sn 100% (Pb Free)				
⑥ Rated Voltage	10 V	⑨ Product	Normal				
⑦ Thickness	1.6 ± 0.2 mm	⑩ Special	Reserved for future use				
		⑪ Packaging	Embossed Type,13"reel(8,000ea)				

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz \pm 10% 1.0 \pm 0.2Vrms
Tan δ (DF)	0.05 max.	
Insulation Resistance	More than 100Mohm $\cdot\mu$ F	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Visual inspection
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characteristics	X7R (From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change should be within \pm 15%)	
Adhesive Strength of Termination	No peeling shall occur on the terminal electrode	500g \cdot F, for 10 \pm 1 sec.
Bending Strength	Capacitance change : within \pm 12.5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245 \pm 5 $^{\circ}$ C, 3 \pm 0.3sec. (preheating : 80~120 $^{\circ}$ C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within \pm 7.5% Tan δ , IR : initial spec.	Solder pot : 270 \pm 5 $^{\circ}$ C, 10 \pm 1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours \times 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.075 max IR : More than $25\text{M}\Omega \cdot \mu\text{F}$	With rated voltage $40 \pm 2^\circ\text{C}$, 90~95%RH, 500+12/-0 hours
High Temperature Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.075 max IR : More than $50\text{M}\Omega \cdot \mu\text{F}$	With 200% of the rated voltage Max. operating temperature 1000+48/-0 hours
Temperature Cycling	Capacitance change : within $\pm 7.5\%$ Tan δ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^\circ\text{C}$ \rightarrow Max. operating temperature $\rightarrow 25^\circ\text{C}$ 5 cycles test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : $260 \pm 0/-5^\circ\text{C}$, 10sec. Max)

* For more detailed Specification, Please refer to the Samsung MLCC catalogue.